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	U.S. UTILITY Patent Application
	O.I.P.E. PATENT DATE SCANNED Q.A.M.9 EXAMINER
APF	O9/830253 D F O29 SUBCLASS ART UNIT
APPLICANTS	Francis Bourrieres
TITLE APPL	Method for making electronic modules with ball connector or with integrated preforms capable of being soldered on a printed circuit integrated preforms capable of being soldered on a printed circuit integrated preforms capable of being soldered on a printed circuit integrated preforms capable of being soldered on a printed circuit

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ORIGINAL			CROSS REFERENCE(S)					
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TERMINAL	DRAWINGS			CLAIMS ALLOWED		
DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
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subsequent to (date) has been disclaimed.	(Assistant	Examiner)	(Date)			
The term of this patent shall						
not extend beyond the expiration date of U.S Patent. No.			ISSUE FEE			
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this patent have been disclaimed.	(Legal Instrum	ents Examiner)	(Date)		<u> </u>	
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